



Material Content Data Sheet



Sales Product Name				BSC109N10NS3 G		Issued		20. July 2018	
MA#				MA001617518					
Package				PG-TDSON-8-39		Weight*		118.00 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.461	2.09	2.09	20855	20855	
leadframe	non noble metal	iron	7439-89-6	0.049	0.04		416		
	inorganic material	phosphorus	7723-14-0	0.015	0.01		125		
	non noble metal	copper	7440-50-8	49.082	41.59	41.64	415947	416491	
wire	non noble metal	copper	7440-50-8	0.062	0.05	0.05	523	523	
encapsulation	organic material	carbon black	1333-86-4	0.078	0.07		662		
	plastics	epoxy resin	-	6.172	5.23		52309		
	inorganic material	silicondioxide	60676-86-0	32.816	27.81	33.11	278100	331071	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12302	12302	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1403	1403	
solder	noble metal	silver	7440-22-4	0.057	0.05		486		
	non noble metal	tin	7440-31-5	0.046	0.04		389		
	non noble metal	lead	7439-92-1	2.192	1.86	1.95	18579	19454	
heatspreader	non noble metal	copper	7440-50-8	0.000	0.00		1		
	non noble metal	iron	7439-89-6	0.000	0.00		1		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.00	1	0	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		189		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		57		
	noble metal	silver	7440-22-4	1.032	0.87		8742		
	non noble metal	copper	7440-50-8	22.292	18.89	19.79	188913	197901	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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